Material Composition Specification

DO-35 Case

Device average mass . . . . . 136 mg

Fluctuation margin . . . . . +/-10%

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	0.018%	0.024	Si	7440-21-3	0.013%	0.018	132
				Ag	7440-22-4	0.004%	0.006	44
leadframe	metal alloy	72.618%	98.76	Fe	7439-89-6	48.787%	66.35	487,868
				Cu	7440-50-8	21.162%	28.78	211,618
				Ni	7440-02-0	2.669%	3.63	26,691
encapsulation	glass	25.103%	34.14	SiO_2	14808-60-7	10.044%	13.66	100,441
				PbO	1317-36-8	15.059%	20.48	150,588
plating*	tin/lead process	2.235%	3.04	Sn	7440-31-5	1.788%	2.432	17,882
				Pb	7439-92-1	0.447%	0.608	4,471
	100% tin process	2.235%	3.04	Sn	7440-31-5	2.235%	3.04	22,353
ink	N/A	0.026%	0.036	tributyl-phosphate	126-73-8	0.016%	0.022	162
				carbon black	1333-96-4	0.004%	0.005	37
				phenol	108-95-2	0.001%	0.001	7
				Proprietary	--	0.006%	0.008	59

*For Lead Free plating, add suffix “LEAD FREE” to part number.
For Tin/Lead plating, add suffix “TIN/LEAD” to part number.
No suffix designation allows for the supply of either lead-free or tin/lead plated product depending on availability.